

NCE Automotive N-Channel Super Trench II Power MOSFET

Description

The series of devices uses **Super Trench II** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{\text{DS(ON)}}$ and Q_g . This device is ideal for high-frequency switching and synchronous rectification.

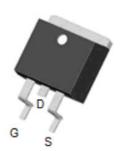
Application

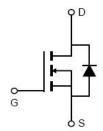
- Automotive application
- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

General Features

- V_{DS} =85V,I_D =220A
 R_{DS(ON)}=2.4mΩ , typical @ V_{GS}=10V
- Excellent gate charge x R_{DS(on)} product(FOM)
- Very low on-resistance R_{DS(on)}
- 175°C operating temperature
- Pb-free lead plating
- 100% UIS tested
- 100% ∆Vds tested
- AEC-Q101 qualified







Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
AP028N85D	NCEAP028N85D	TO-263	-	-	-

Absolute Maximum Ratings (T_c=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	85	V
Gate-Source Voltage	V _G s	±20	V
Drain Current-Continuous	I _D	220	А
Drain Current-Continuous(T _C =100 ℃)	I _D (100°C)	155	Α
Pulsed Drain Current	I _{DM}	880	А
Maximum Power Dissipation	P _D	245	W
Derating factor		1.63	W/℃
Single pulse avalanche energy (Note 1)	E _{AS}	1767	mJ
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55 To 175	$^{\circ}$

Thermal Characteristic

Thermal Resistance,Junction-to-Case	R _{eJC}	0.61	°C/W



Electrical Characteristics (T_C=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit	
Off Characteristics							
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	85	-	-	V	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =85V,V _{GS} =0V	-	-	1	μA	
Gate-Body Leakage Current	I _{GSS}	V_{GS} =±20 V , V_{DS} =0 V	-	-	±100	nA	
On Characteristics			•			•	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS},I_{D}=250\mu A$	2.0	3.0	4.0	V	
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =100A	-	2.4	2.8	mΩ	
Forward Transconductance	g FS	V _{DS} =5V,I _D =100A	-	200	_	S	
Dynamic Characteristics			•				
Input Capacitance	Clss	V_{DS} =40V, V_{GS} =0V, F=1.0MHz	-	7680	-	PF	
Output Capacitance	Coss		-	1472	-	PF	
Reverse Transfer Capacitance	C _{rss}	F=1.UIVIH2	-	60	-	PF	
Switching Characteristics (Note 2)							
Turn-on Delay Time	t _{d(on)}		-	25	-	nS	
Turn-on Rise Time	t _r	V_{DD} =40 V , I_D =100 A	-	15	-	nS	
Turn-Off Delay Time	t _{d(off)}	V_{GS} =10 V , R_{G} =1.6 Ω	-	52	-	nS	
Turn-Off Fall Time	t _f		-	17	-	nS	
Total Gate Charge	Qg	\/ 40\/ I 400A	-	124	-	nC	
Gate-Source Charge	Q _{gs}	V _{DS} =40V,I _D =100A, V _{GS} =10V	-	37	-	nC	
Gate-Drain Charge	Q _{gd}		-	33	-	nC	
Drain-Source Diode Characteristics			•				
Diode Forward Voltage	V _{SD}	V _{GS} =0V,I _S =100A	-	-	1.2	V	
Diode Forward Current	Is		-	-	220	Α	
Reverse Recovery Time	t _{rr}	T _J = 25°C, I _F = 100A	-	98	-	nS	
Reverse Recovery Charge	Qrr	di/dt = 100A/µs	-	280	-	nC	

Notes:

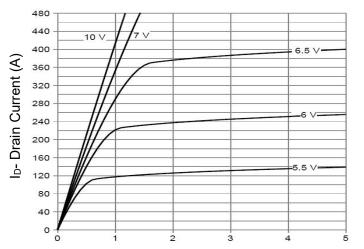
^{1.}EAS condition : Tj=25 $^{\circ}\mathrm{C}$,V $_{DD}$ =40V,V $_{G}$ =10V,L=0.5mH,Rg=25 Ω

^{2.} Guaranteed by design, not subject to production

^{3.}These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of TJ(MAX)=175° C. The SOA curve provides a single pulse rating.

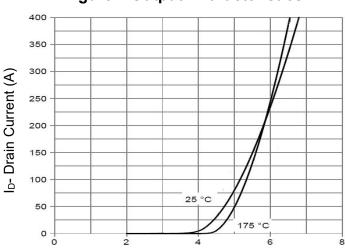


Typical Electrical and Thermal Characteristics



Vds Drain-Source Voltage (V)

Figure 1 Output Characteristics



Vgs Gate-Source Voltage (V)

Figure 2 Transfer Characteristics

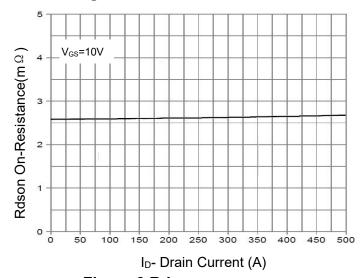
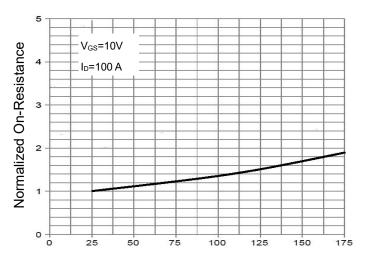
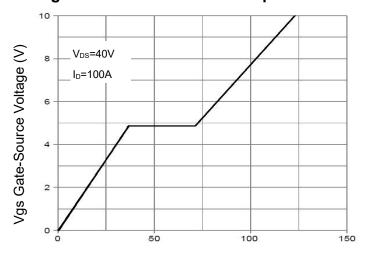


Figure 3 Rdson- Drain Current

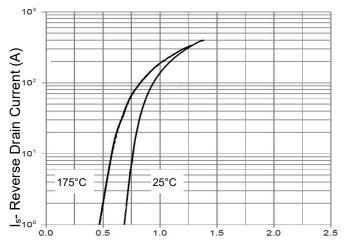


T_J-Junction Temperature(°C)

Figure 4 Rdson-Junction Temperature



Qg Gate Charge (nC)
Figure 5 Gate Charge



Vsd Source-Drain Voltage (V)

Figure 6 Source- Drain Diode Forward



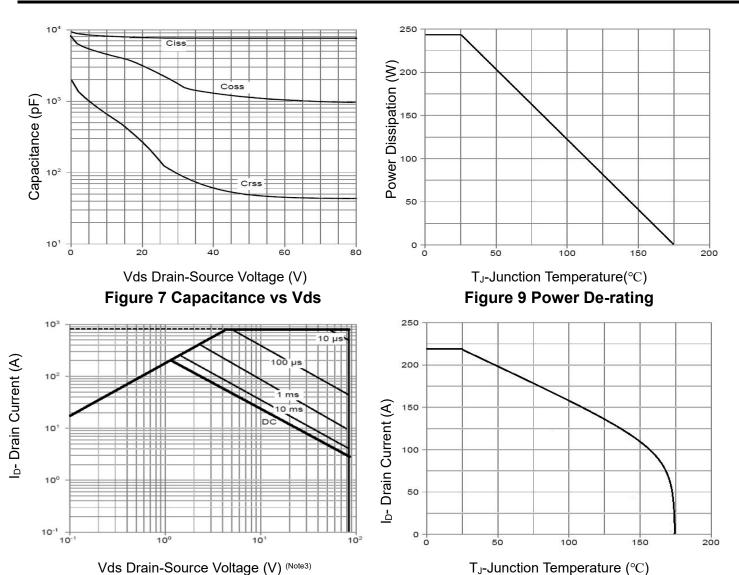
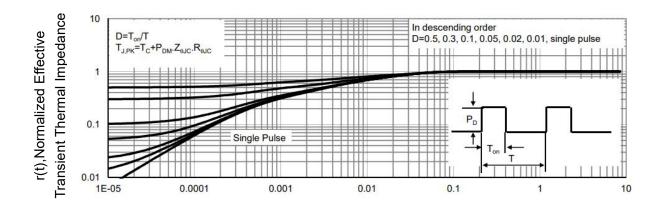


Figure 8 Safe Operation Area

Figure 10 Current De-rating

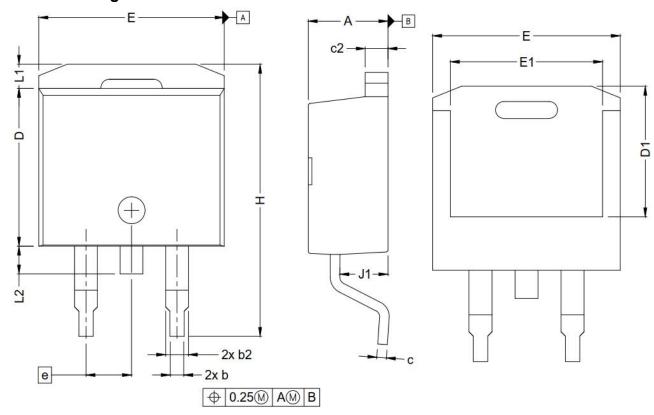


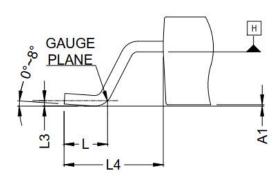
Square Wave Pluse Duration(sec)

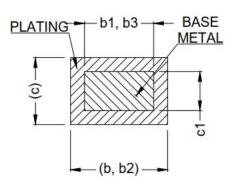
Figure 11 Normalized Maximum Transient Thermal Impedance



TO-263-2L Package Information







SYMBOL	MIN.	MAX.	SYMBOL	MIN.	MAX.
A	4.36	4.56	E	10.15	10.55
A1	0	0.25	E1	8.10	8.70
b	0.70	0.90	e	2.54	BSC
b1	0.51	0.89	H	15.00	15.60
b2	1.17	1.37	L	1.90	2.50
b3	1.17	1.37	L1	-	1.65
С	0.38	0.69	L2	-	1.78
c1	0.38	0.53	L3	0.25	ГҮР
c2	1.19	1.34	L4	4.78	5.28
D	8.60	9.00	J1	2.56	2.96
D1	6.90	7.50			



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